Quik-Pak, Promex Promote Advanced Packaging, Heterogeneous Assembly at Two Industry Events in New York, Washington D.C., Sept. 19-22, 2017

Electronic Packaging Symposium (EPS), International Conference on Silicon Carbide & Related Materials (ICSCRM) Provide Opportunities to Share Advances, Investigate Future Solutions

Santa Clara, CA – September 19, 2017 — Representatives from Quik-Pak, a provider of microelectronic packaging for complex devices, and its parent company Promex, a provider of IC package development and heterogenous assembly services, and from its will be on the East Coast September 19- 22, 2017 for two industry events.

At the 29th Annual Electronics Packaging Symposium (EPS), September 19-20 in Niskayuna, New York, Quik-Pak will exhibit information about its new San Diego production line for overmolded, open-tooled QFN and DFN packages. The addition of a wirebonder, molding press and laser marker onsite enables Quik-Pak to expedite packaging for quick-turn engineering builds and volume production.

“Considering that the QFN platform has become the package of choice for single die, multi-die, SiPs and stacked die, it makes sense for us to offer an alternative to going offshore for high-volume production,” said Quik-Pak Global Sales and Marketing Director Casey Krawiec.

Following EPS, Promex and Quik-Pak representatives will participate in the 2017 International Conference on Silicon Carbide and Related Materials (ICSCRM) in Washington, D.C. ICSCRM identifies materials and device challenges and discusses applications driving the advancement of SiC technology. The conference is produced by The Materials Research Society (MRS), a member-driven organization of almost 14,000 materials researchers dedicated to the advancement of interdisciplinary materials research.

“ICSCRM’s “moving from niche to mainstream” theme is similar to how we help our customers,” said Promex Director of Sales and Marketing Rosie Medina. “They come to us with a proof of concept for a complex device and we use our materials science-centric experience to specify synergistic IC packaging and assembly processes. The result is a seamless transition from engineering to production.”

ABOUT QUIK-PAK
Quik-Pak, a division of Promex, provides IC packaging, assembly and wafer preparation services in its ISO 9001:2008-certified, ITAR-registered facility in San Diego, California. The company’s overmolded QFN/DFN premolded air cavity QFN packages are available for prototype to full production needs. Same-day assembly services. More information is available at http://www.icproto.com or by calling 858-674-4676.

ABOUT PROMEX

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